

A

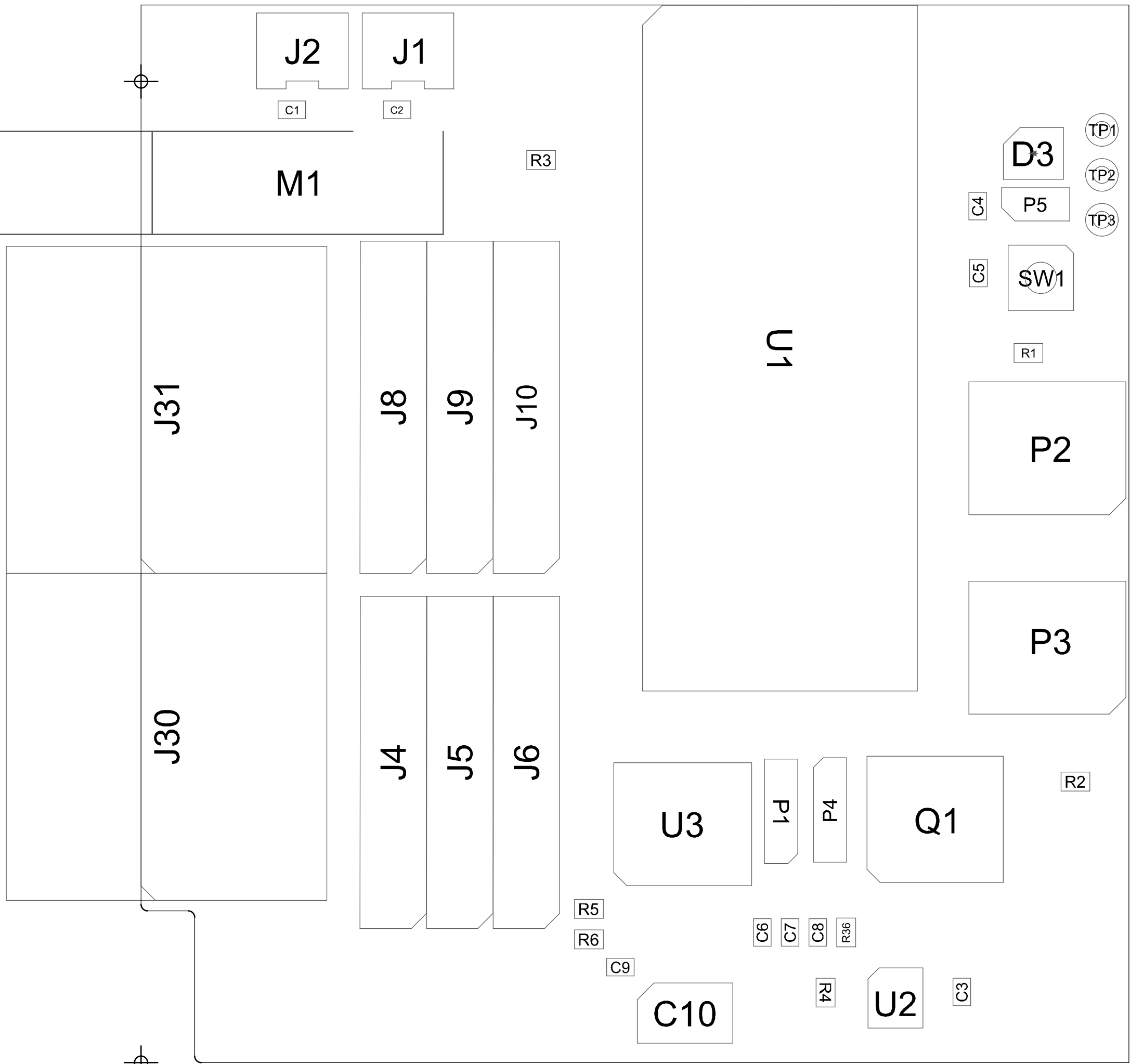
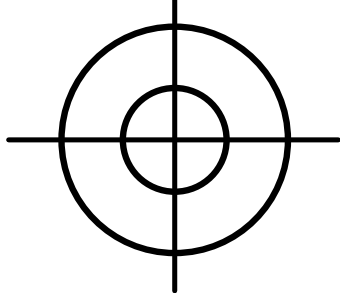
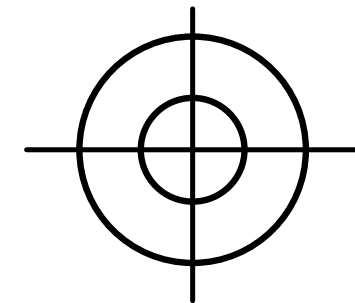
B

C

D

B

D



RTM Bringup Adapter Rev.: 1.1

Layer Legend

Document Template + Board Information (Mechanical2)

Board Outline + Panel information (Mechanical1)

Designator Top

Board Thickness: 1.63mm
Layer Count: 4
Layer Stackup: 'Leiton 4-Layer Multilayer 1,60mm 35um/35um aus DEUTSCHER Fertigung'
Board Material: FR-4 TG170
Smalltest Track: 0.15mm
Smallest Hole: 0.3mm
Surface: NiAu or Immersion Tin
Print Top Overlay (Silkscreen): YES
Print Bottom Overlay (Silkscreen): NO
Board Outline: Milled
Electrical test: YES

License

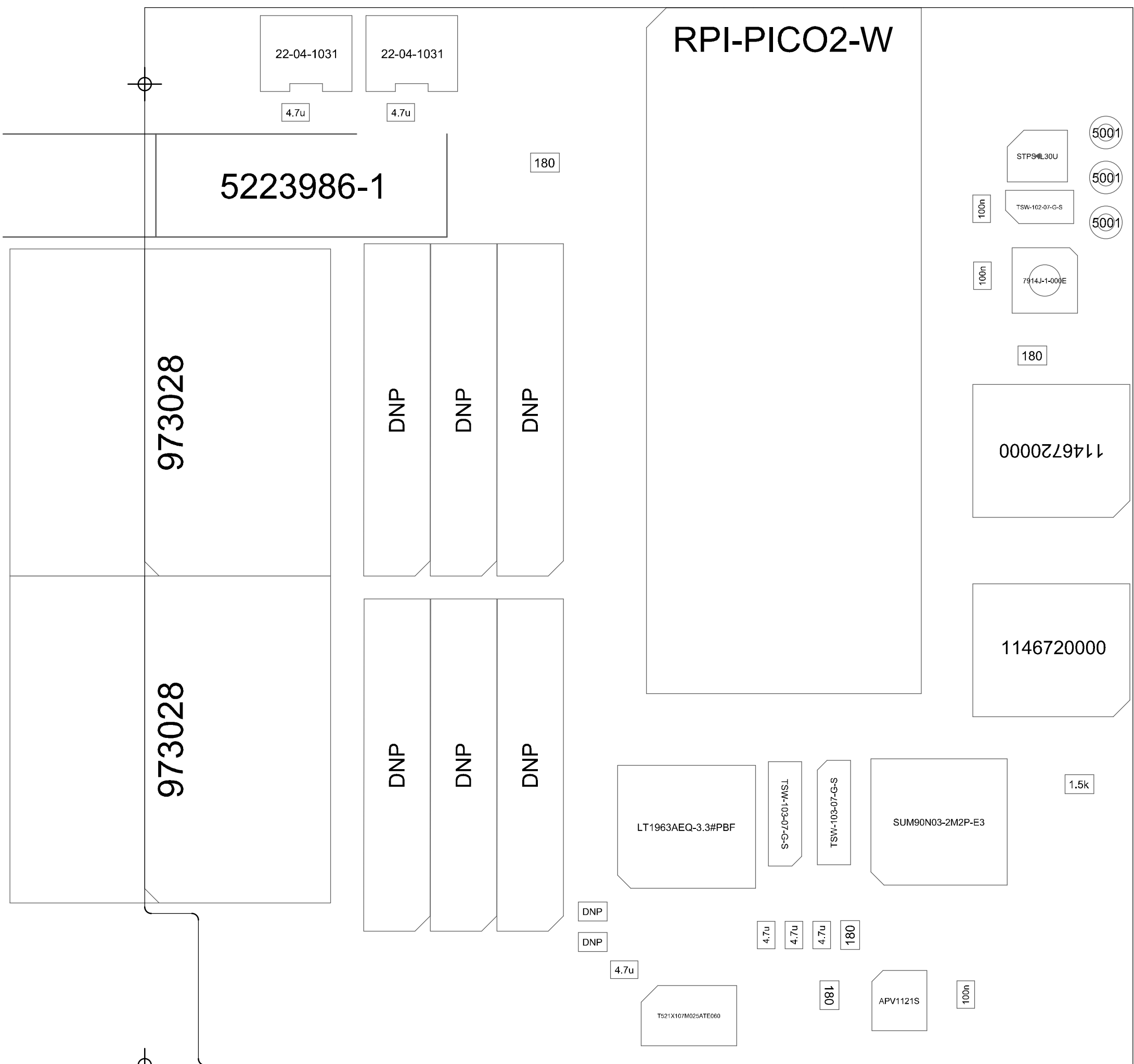
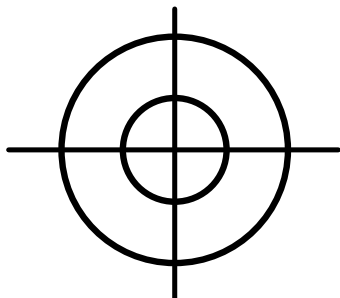
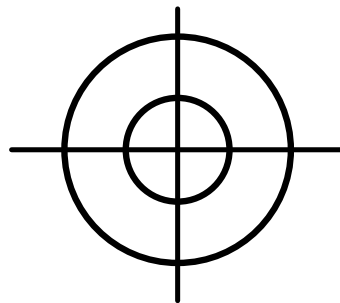
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	DATE: 07/05/2026		LP NO.: —	REV: 1.1
	FILE NAME: RTM_bringup_adapter.PcbDoc		LP Type: 4 Layers	SCALE: SCALE: 1.00



RTM Bringup Adapter Rev.: 1.1

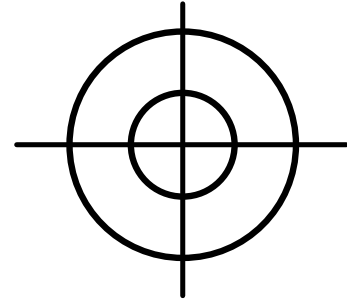
Layer Legend

Document Template + Board Information (Mechanical2)

Board Outline + Panel information (Mechanical1)

Value Top

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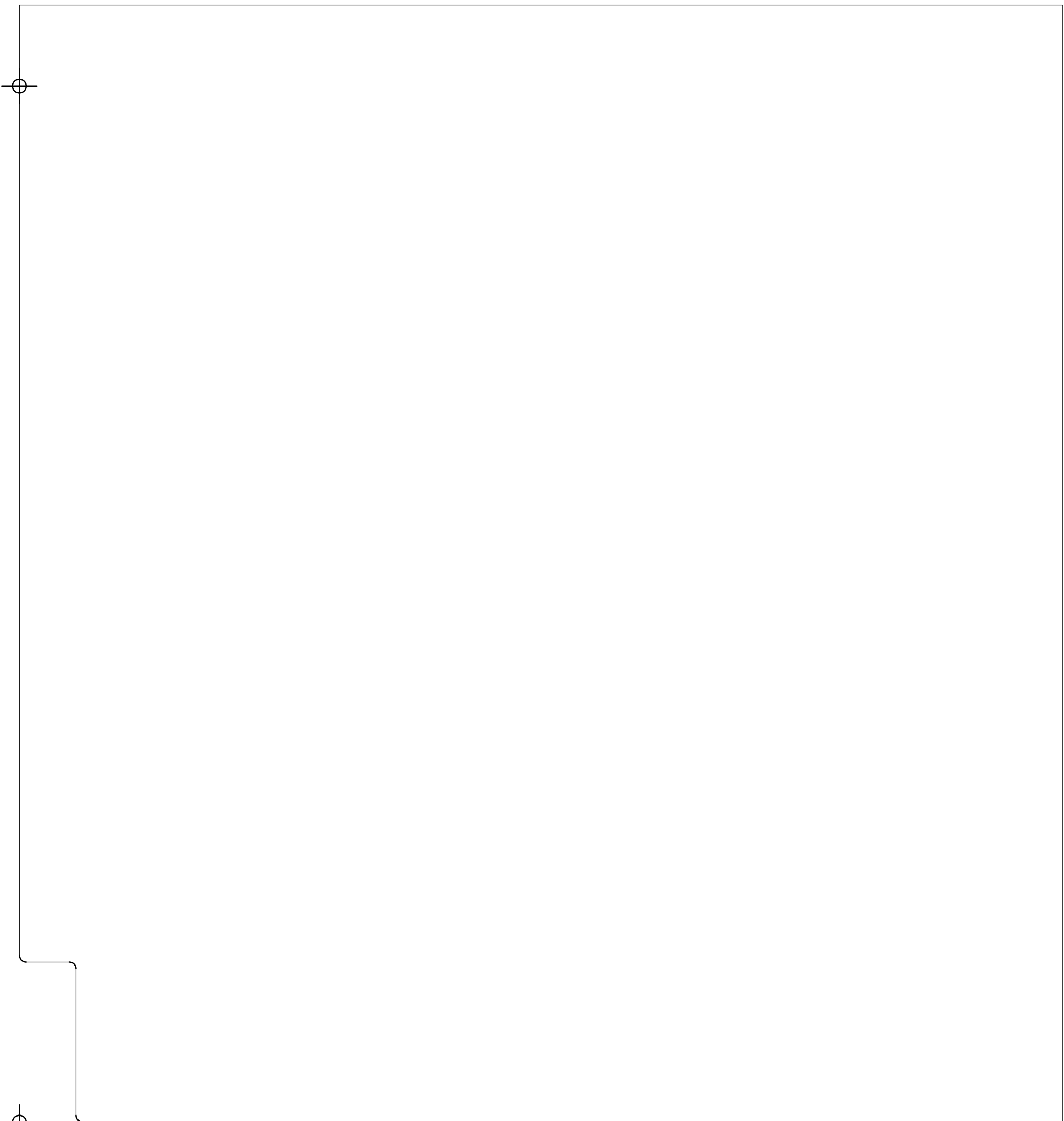
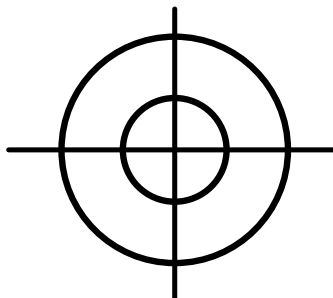
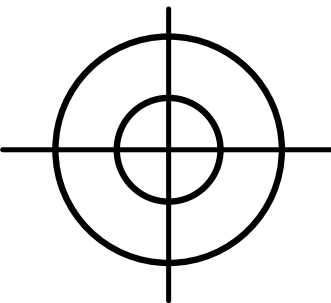
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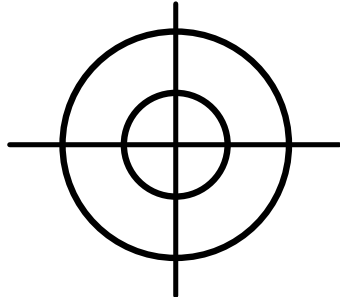
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	FILE NAME: RTM_bringup_adapter.PcbDoc		LP Type: 4 Layers	SCALE: SCALE: 1.00



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Board Outline: Milled
Electrical test: YES



RTM Bringup Adapter Rev.: 1.1

Layer Legend

Document Template + Board Information (Mechanical2)
Board Outline + Panel information (Mechanical1)

Designator Bottom

License

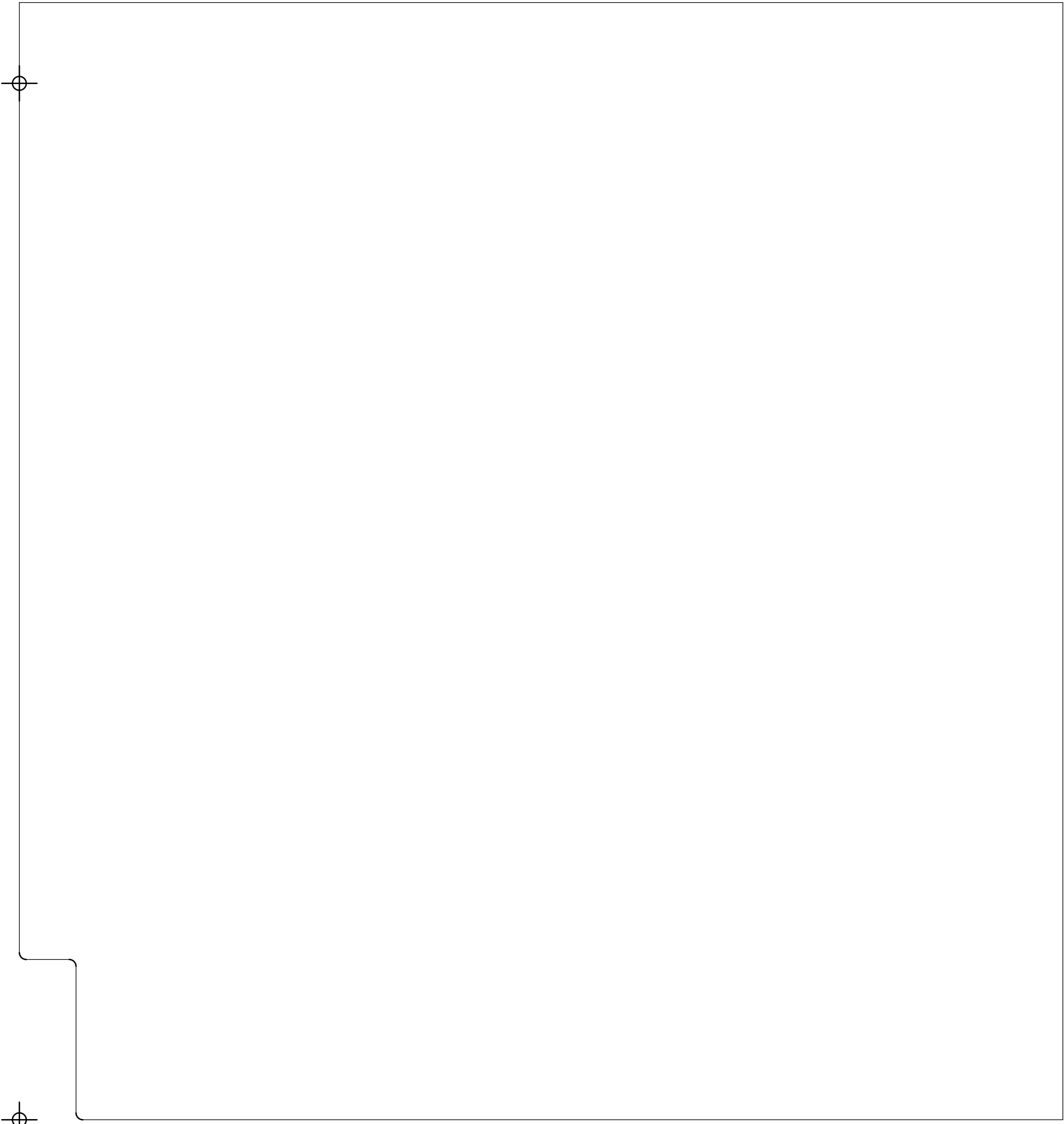
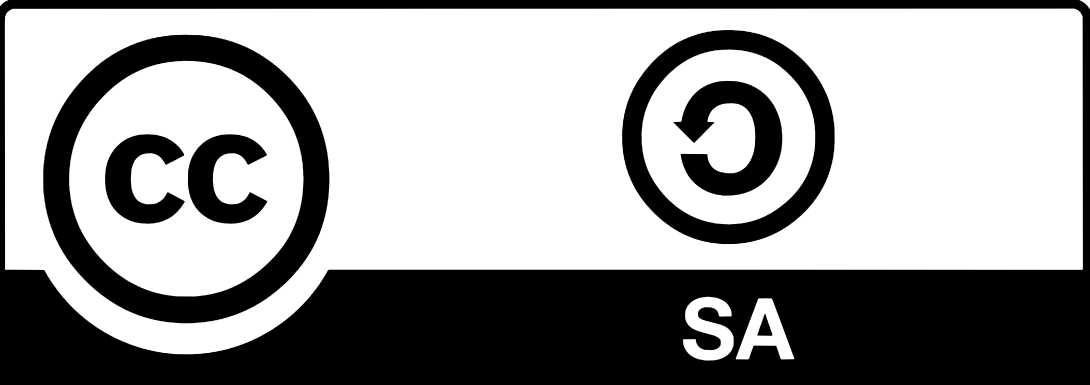
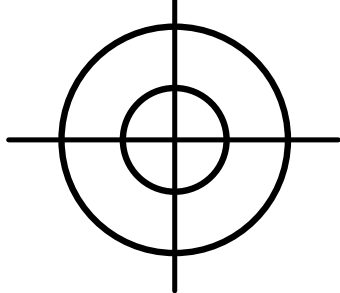
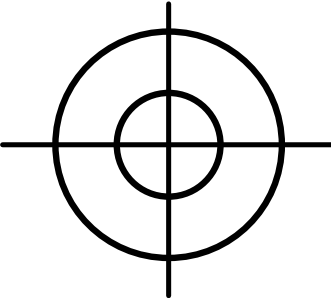
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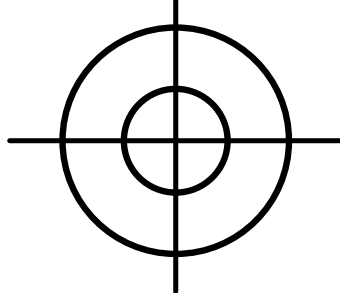
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	DATE: 07/05/2026		LP NO.: —	REV: 1.1
	FILE NAME: RTM_bringup_adapter.PcbDoc		LP Type: 4 Layers	SCALE: SCALE: 1.00



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RTM Bringup Adapter Rev.: 1.1

Layer Legend

Document Template + Board Information (Mechanical2)
Board Outline + Panel information (Mechanical1)

Value Bottom

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